

Specifications

Insulation Resistance:	500MΩ at 150V DC
Withstanding Voltage:	100V _{eff} to 700V _{eff} for 1 minute
Contact Resistance:	30mΩ max. at 10mA and 20mV
Operating Temp. Range:	-25°C to +85°C
Reflow-soldering Temp.:	220°C for 60 seconds
Mating Cycles:	20 insertions maximum
Solvent Durability:	Freon
Allowable Torque (max.):	- for 1-time screw connection = max 0.147 Nm - for repetitive screw connection = min 0.078 Nm max 0.098 Nm

Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0
 Contact: Beryllium Copper (BeCu)
 Plating: SnPb 2.0 ~ 4.0μm over 2.5 ~ 4.5μm Ni = S5
 Au 0.3μm min. over 2.5 ~ 4.5μm Ni = B5

Part Number (Details)

IC149 - 080 - *31 - *5

Series No.

No. of Contact Pins

Positioning Pins:

0 = Without Pins

1 = With Pins

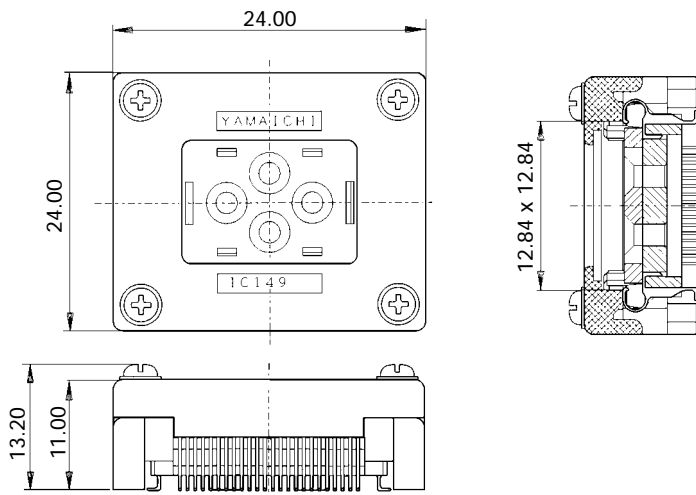
Contact Plating:

S = SnPb (for IC-socket Use)

B = Gold (for Adapter Use)

Compatible Emulation-Adapter ICP-080-6

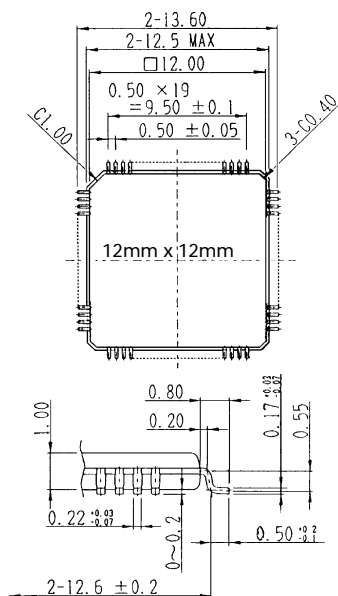
Outline Socket Dimensions (Reference Only)



Remarks

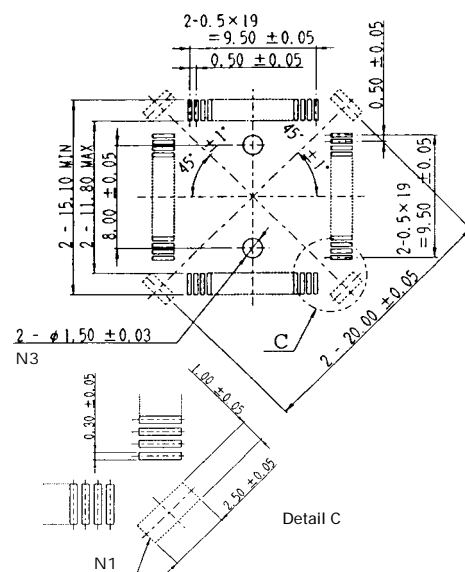
1. Ensure a clean contact area. Fluxes, dust and other impurities may cause corrosion and contact problems.
2. This Socket is not for automatic production. It is particularly suitable for the development of software stored in ROM and for testing LSI-IC's.
3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
4. If using the Socket with an Adapter, please use the gold-plated Socket version.

IC - Dimensions



Socket PCB-Layout

Top View from Socket



Notes

- N1: Metal soldering Tab Clip. Socket may be stabilized by soldering (Reflow) in these 4 areas.
 N3: These holes are only necessary for use with positioning pins.

QFP/TQFP - 80 Pins (20x20) 0.5mm pitch

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Withstanding Voltage:	100V _{eff} to 700V _{eff} for 1 minute
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IC149 - 080 - *30 - *5

No. of Contact Pins

Positioning Pins:

0 = Without Pins

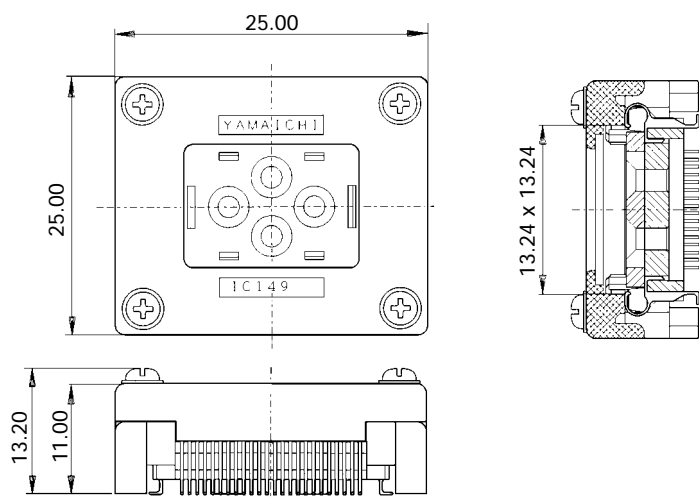
1 = With Pins

Contact Plating:

S = SnPb (for IC-socket Use)

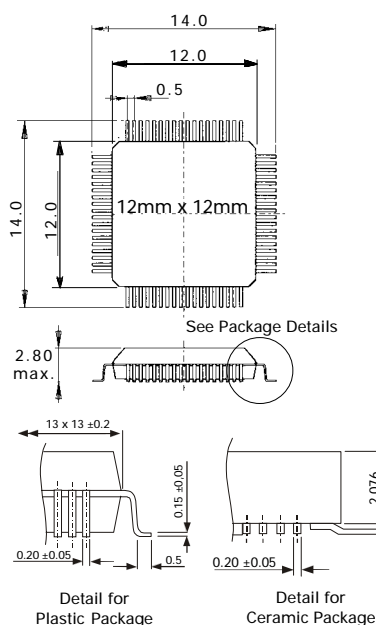
B = Gold (for Adapter Use)

Outline Socket Dimensions (Reference Only)



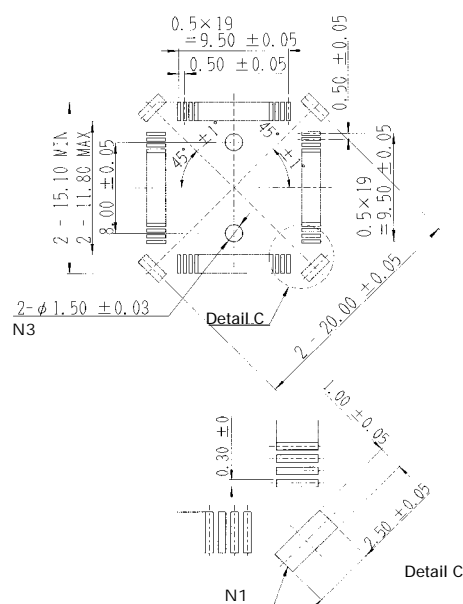
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IC - Dimensions



Socket PCB-Layout

Top View from Socket



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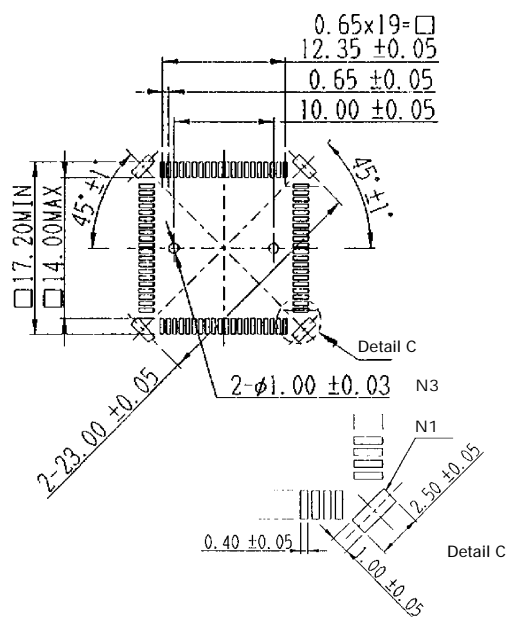
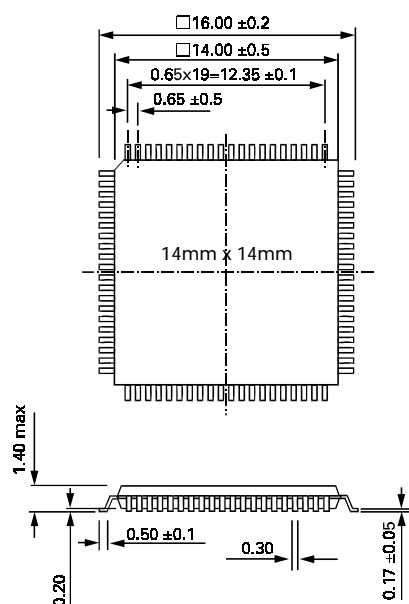
QFP/TQFP - 80 Pins (20x20) 0.65mm pitch

Insulation Resistance:	500MΩ at 150V DC
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4. If using the Socket with an Adapter, please use the gold-plated Socket version.



N1: Metal soldering Tab Clip. Socket may be stabilized by soldering (Reflow) in these 4 areas.
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QFP/TQFP - 80 Pins (20x20) 0.65mm pitch

Insulation Resistance:	500MΩ at 150V DC
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Mating Cycles:	20 insertions maximum
Solvent Durability:	Freon
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Contact: Beryllium Copper (BeCu)
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Au 0.3µm min. over 2.5 ~ 4.5µm Ni = B5

IC149 - 080 - *17 - *5

No. of Contact Pins

Positioning Pins:

0 = Without Pins

1 = With Pins

Contact Plating:

S = SnPb (for IC-socket Use)

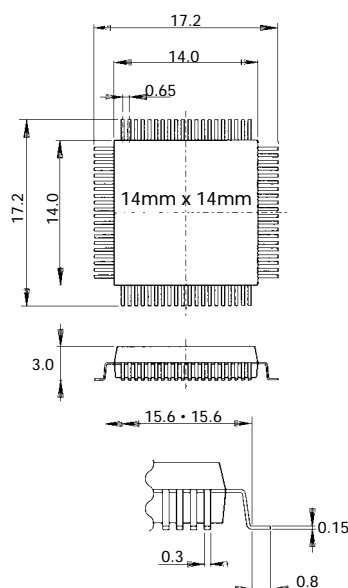
B = Gold (for Adapter Use)

Outline Socket Dimensions (Reference Only)



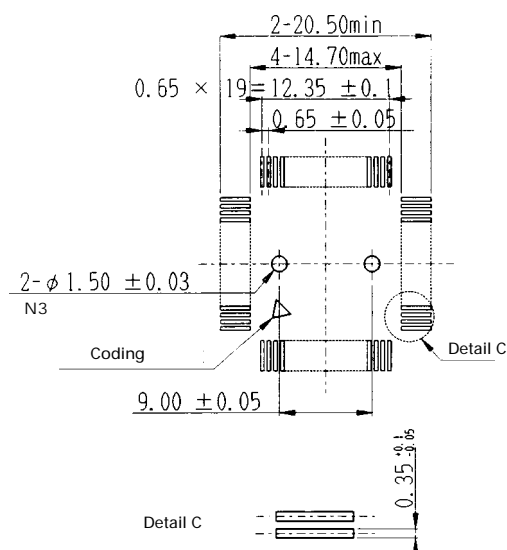
1. Ensure a clean contact area. Fluxes, dust and other impurities may cause corrosion and contact problems.
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3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
4. If using the Socket with an Adapter, please use the gold-plated Socket version.

IC - Dimensions



Socket PCB-Layout

Top View from Socket



Notes

Notes
N3: These holes are only necessary for use with positioning pins.

Specifications

Insulation Resistance:	500MΩ at 150V DC
Withstanding Voltage:	100V _{eff} to 700V _{eff} for 1 minute
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Solvent Durability:	Freon
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Materials and Finish

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0
 Contact: Beryllium Copper (BeCu)
 Plating: SnPb 2.0 ~ 4.0μm over 2.5 ~ 4.5μm Ni = S5
 Au 0.3μm min. over 2.5 ~ 4.5μm Ni = B5

Part Number (Details)

IC149 - 080 - *21 - *5

Series No.

No. of Contact Pins

Positioning Pins:

0 = Without Pins

1 = With Pins

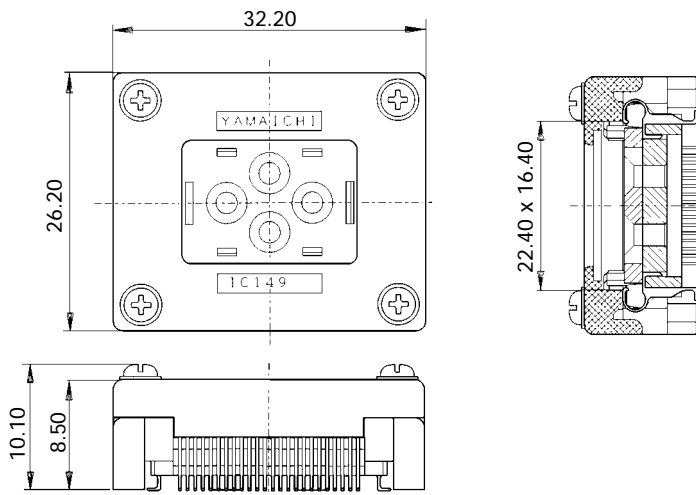
Contact Plating:

S = SnPb (for IC-socket Use)

B = Gold (for Adapter Use)

Compatible Emulation-Adapter ICP-080-5

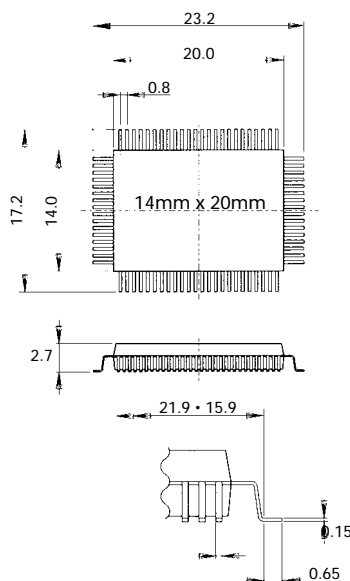
Outline Socket Dimensions (Reference Only)



Remarks

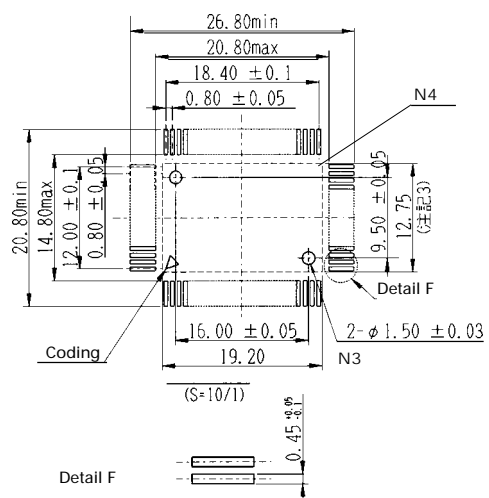
1. Ensure a clean contact area. Fluxes, dust and other impurities may cause corrosion and contact problems.
2. This Socket is not for automatic production. It is particularly suitable for the development of software stored in ROM and for testing LSI-IC's.
3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
4. If using the Socket with an Adapter, please use the gold-plated Socket version.

IC - Dimensions



Socket PCB-Layout

Top View from Socket



Notes

- N3: These holes are only necessary for use with positioning pins.
 N4: The Socket may be glued to the PC Board within this area.

QFP/TQFP - 80 Pins (16x24) 0.8mm pitch

Insulation Resistance:	500MΩ at 150V DC
Withstanding Voltage:	100V _{eff} to 700V _{eff} for 1 minute
Contact Resistance:	30mΩ max. at 10mA and 20mV
Operating Temp. Range:	-25°C to +85°C
Reflow-soldering Temp.:	220°C for 60 seconds
Mating Cycles:	20 insertions maximum
Solvent Durability:	Freon
Allowable Torque (max.):	- for 1-time screw connection = max 0.147 Nm - for repetitive screw connection = min 0.078 Nm max 0.098 Nm

Housing: Polyphenylenesulfide (PPS) glass filled UL94V-0
Contact: Beryllium Copper (BeCu)
Plating: SnPb 2.0 ~ 4.0µm over 2.5 ~ 4.5µm Ni = S5
Au 0.3µm min. over 2.5 ~ 4.5µm Ni = B5

IC149 - 080 - *12 - *5

No. of Contact Pins

Positioning Pins:

0 = Without Pins

1 = With Pins

Contact Plating:

S = SnPb (for IC-socket Use)

B = Gold (for Adapter Use)

Compatible Emulation-Adapter

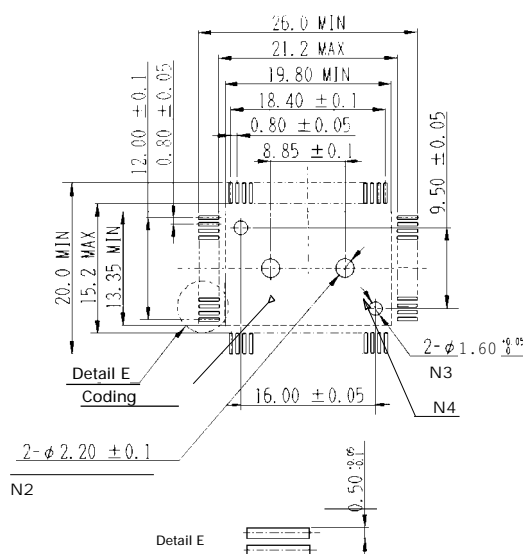
ICP-080-3

1. Ensure a clean contact area. Fluxes, dust and other impurities may cause corrosion and contact problems.
2. This Socket is not for automatic production. It is particularly suitable for the development of software stored in ROM and for testing LSI-IC's.
3. Careful attention must be taken when fixing the Socket, since it is entirely made from thermoplastic material. If the max. torque is exceeded, the Socket will be damaged beyond repair.
4. If using the Socket with an Adapter, please use the gold-plated Socket version.

Technical drawing of a component with dimensions:

- Overall width: 24.8 ± 0.4
- Overall height: 20.0 ± 0.2
- Central rectangular area: $14\text{mm} \times 20\text{mm}$
- Top edge feature: 0.8
- Left side features: 18.8 ± 0.4 and 14.0 ± 0.2
- Bottom edge feature: 3.05 max.
- Bottom edge dimensions: $22.9 \cdot 17.0$
- Bottom edge feature: 0.35
- Bottom edge feature: 0.15

Top View from Socket



N1: Metal soldering Tab Clip. Socket may be stabilized by soldering (Reflow) in these 4 areas.
N2: These holes are only necessary when fixing the Socket with screws.
N3: These holes are only necessary for use with positioning pins.
N4: The Socket may be glued to the PC Board within this area.